### **General Description**

The SJD30P019 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

#### **Features**

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### **Application**

- Load Switch
- IPWM Application
- Power Management

### **Key Performance Parametes**

Parameter	Value	Unit
V <sub>DS</sub>	-30	V
R <sub>DS(ON)_TYP</sub>	2.8	mΩ
ID	-173	Α
Q <sub>G</sub>	210	nC



### **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD30P019	SJD30P019	TO-252	Tape	\	1	2500 Pcs

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> =0V)	-30	V
Vgs	Gate-Source Voltage (V <sub>DS</sub> =0V)	±20	V
1-	Drain Current-Continuous(Tc=25℃)	-173	А
I <sub>D</sub>	Drain Current-Continuous(Tc=100℃)	-109	А
I <sub>DM</sub> (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-692	А
D	Maximum Power Dissipation(Tc=25°ℂ)	167	W
P <sub>D</sub>	Maximum Power Dissipation(T <sub>C</sub> =100℃)	67	W
Eas	Avalanche energy (Note 2)	1056	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	င

#### Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R <sub>θ</sub> JC	Thermal Resistance, Junction-to-Case		0.75	°C/W



Table 3. Electrical Characteristics (T<sub>J</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-30			V
	7 0 1 1/4 5 1 0 1	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C			-1	μA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V T <sub>J</sub> =125°C			-100	μA
Igss	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1		-2.5	V
<b>g</b> FS	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-20A		54		S
		V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A		2.8	3.5	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A		3.7	4.9	mΩ
Dynamic Chara	cteristics					
Ciss	Input Capacitance			12755		pF
Coss	Output Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1.0MHz		1330		pF
Crss	Reverse Transfer Capacitance			1202		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		1.8		Ω
Switching Parai	meters					
t <sub>d(on)</sub>	Turn-on Delay Time			19.5		nS
t <sub>r</sub>	Turn-on Rise Time	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =0.75Ω, R <sub>GEN</sub> =3Ω		4		nS
$t_{d(off)}$	Turn-Off Delay Time			22.5		nS
t <sub>f</sub>	Turn-Off Fall Time			37.4		nS
Qg	Total Gate Charge			210		nC
Qgs	Gate-Source Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A		24		nC
$Q_{gd}$	Gate-Drain Charge			31		nC
Source-Drain D	iode Characteristics		•	•	•	
I <sub>SD</sub>	Source-Drain Current (Body Diode)				-173	Α
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =-20A			-1.2	٧
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-20A, di/dt=-100A/µs		39		ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =-20A, di/dt=-100A/μs		29.3		nC

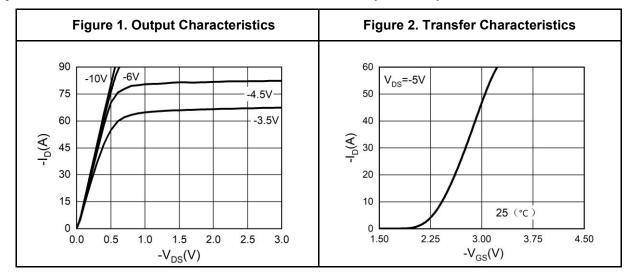
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

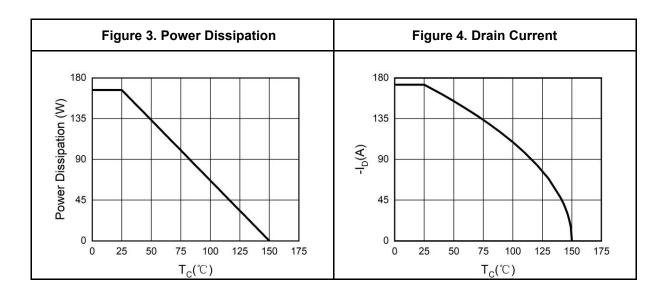
Notes 2.E<sub>AS</sub> condition:  $T_J=25^{\circ}C$ ,  $V_{DD}=-30V$ ,  $V_{G}=-10V$ ,  $Rg=25\Omega$ , L=0.5mH.

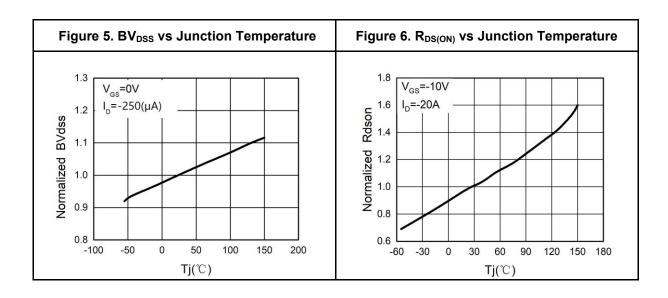
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



# **Typical Electrical And Thermal Characteristics (Curves)**

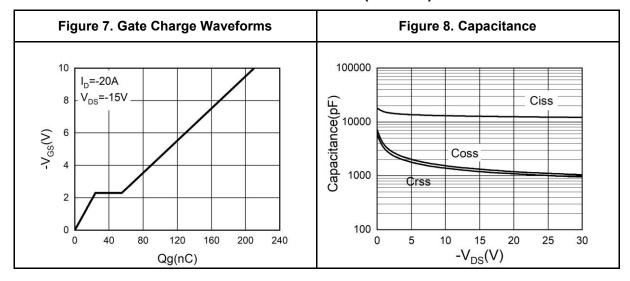


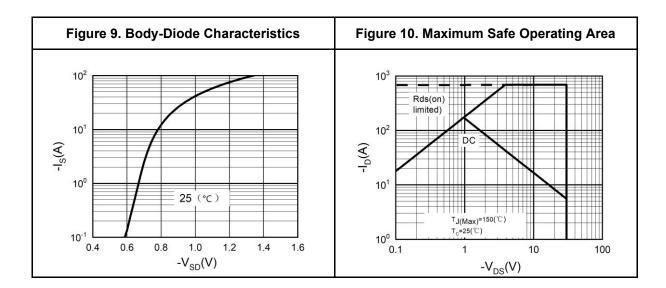






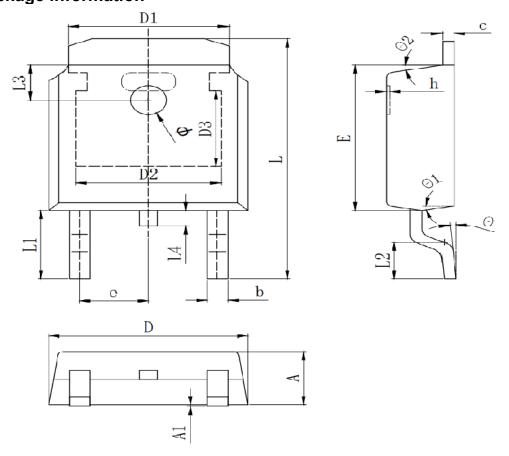
# **Typical Electrical And Thermal Characteristics (Curves)**







# **TO-252 Package Information**



Symbol	Dimensions In Millimeters				
Symbol	Min.	Тур.	Max.		
Α	2.200	2.300	2.400		
A1	0.000		0.127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6.700		
D1		5.334 REF			
D2		4.826 REF			
D3		3.166 REF			
E	6.000	6.100	6.200		
е		2.286 TYP			
h	0.000	0.100	0.200		
L	9.900	10.100	10.300		
L1		2.888 REF			
L2	1.400	1.550	1.700		
L3		1.600 REF			
L4 0.600		0.800	1.000		
Ф	1.100	1.200	1.300		
θ	0°		8°		
θ1		9° TYP			
θ2	9° TYP				

### **Attention**

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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